

RESIN MOLDING APPARATUS AND PRODUCTION METHOD FOR RESIN MOLDED ARTICLE

ABSTRACT

The present invention is intended to reduce product defects such as a failure in removing an unnecessary resin remaining on a sealed substrate from which unnecessary resin including at least a cull has been removed, or chipping of a package, when the unnecessary resin is removed. The present invention includes a resin molding unit B that forms a sealed substrate W1 by sealing a substrate W with resin; and removing units C, D that remove unnecessary resin K1, K2 from the sealed substrate W1. The removing unit D includes a reversing conveyor mechanism 2 including a substrate holding unit 3 that holds the sealed substrate W1 from which first unnecessary resin K1 including at least cull has been removed, a reversing unit 4 that rotates the substrate holding unit 3 to reverse the sealed substrate W1 topside down, and a substrate conveyor unit 5 that conveys the sealed substrate W1 having been reversed topside down by the reversing unit 4, to a processing stage 111 for removing second unnecessary resin K2 remaining on the sealed substrate W1.

FIG. 7